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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/731,494	12/09/2003	Arvind Halliyal	AF01194	4623
45305	7590 02/04/2005		EXAM	INER
RENNER, OTTO, BOISSELLE & SKLAR, LLP (AMDS)			COLEMAN, WILLIAM D	
	1621 EUCLID AVE - 19TH FLOOR CLEVELAND, OH 44115-2191		ART UNIT	PAPER NUMBER
022.22.	,		2823	·

DATE MAILED: 02/04/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
	10/731,494	HALLIYAL ET AL.			
Office Action Summary	Examin r	Art Unit			
	W. David Coleman	2823			
The MAILING DATE of this communication a Period for Reply	appears on the cover sheet with th	correspond nce address			
A SHORTENED STATUTORY PERIOD FOR REF THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a r - If NO period for reply is specified above, the maximum statutory perions - Failure to reply within the set or extended period for reply will, by state that the period for reply will, by state that the material patent term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no event, however, may a reply be ti- reply within the statutory minimum of thirty (30) da od will apply and will expire SIX (6) MONTHS fron tute, cause the application to become ABANDONI	mely filed ys will be considered timely. n the mailing date of this communication. ED (35 U.S.C. § 133).			
Status					
 1) ⊠ Responsive to communication(s) filed on 24 2a) ☐ This action is FINAL. 2b) ⊠ This action is FINAL. 2b in accordance with the practice under t	his action is non-final. vance except for formal matters, pr				
Disposition of Claims					
4) ☐ Claim(s) 1-20 is/are pending in the application 4a) Of the above claim(s) is/are withd 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1,3-6,8-10,12-15 and 17-20 is/are is/are objected to. 7) ☐ Claim(s) 2,7,11 and 16 is/are objected to. 8) ☐ Claim(s) are subject to restriction and	rawn from consideration.				
9)☐ The specification is objected to by the Exam					
	10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.				
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
Replacement drawing sheet(s) including the corr					
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for forei a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the p application from the International Bure * See the attached detailed Office action for a l	ents have been received. ents have been received in Applica riority documents have been receiv eau (PCT Rule 17.2(a)).	tion No red in this National Stage			
Attachment(s) 1) Notice of References Cited (PTO-892)	4) 🔲 Interview Summar	y (PTO-413)			
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/Paper No(s)/Mail Date 03/04. 	Paper No(s)/Mail [

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DETAILED ACTION

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Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

3. Claims 1, 8, 9, 10, 17 and 18 are rejected under 35 U.S.C. 102(e) as being anticipated by Tanaka et al., U.S. Patent 6,767,796 B2.

<u>Tanaka</u> discloses a semiconductor process as claimed. See **FIGS. 1A-24**, where <u>Tanaka</u> teaches the claimed limitations.

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FIG.11A

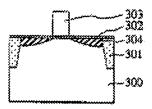
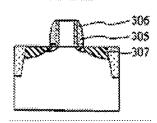


FIG.11B



4. Pertaining to claim 1, <u>Tanaka</u> teaches a process for fabricating a semiconductor device comprising:

providing a semiconductor substrate 300 having formed thereon a semiconductor device (not numbered, however, a gate insulator 302, gate electrode 303 and source drain 307 are disclosed as what is known as a MOSFET);

depositing over the semiconductor device a spacer layer 305/306, the spacer layer having a first hydrogen content (see FIG. 17); and

applying a treatment to reduce the first hydrogen content to a second hydrogen content.

5. Pertaining to claim 8, <u>Tanaka</u> teaches the process of claim 1, wherein the treatment is applied to the spacer layer, prior to etching to form a spacer for the semiconductor device (the Examiner takes the position that the first sidewall layer is the on formed after the ldd is formed and activated).

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6. Pertaining to claim 9, <u>Tanaka</u> teaches the process of claim 1, wherein the process further comprises a step of etching to form a spacer for the semiconductor device, and the treatment is applied to the spacer subsequent to the etching step.

Pertaining to claim 10, <u>Tanaka</u> teaches a process for fabricating a charge trapping dielectric flash memory device comprising:

providing a semiconductor substrate having formed thereon a gate stack comprising a charge trapping dielectric charge storage layer and a control gate electrode overlying the charge trapping dielectric charge storage layer;

depositing over the gate stack a spacer layer, the spacer layer having a first hydrogen content; and applying a treatment to reduce the first hydrogen content of at least a portion of the spacer layer to a second hydrogen content (see the art rejection as applied to claim 1 above and FIGS.23A-23B).

- 7. Pertaining to claim 17, <u>Tanaka</u> teaches the process of claim 10, wherein the treatment is applied to the spacer layer, prior to an etching step for forming a gate stack spacer.
- 8. Pertaining to claim 18, <u>Tanaka</u> teaches the process of claim 1, wherein the treatment is applied to the gate stack spacer subsequent to an etching step for forming a gate stack spacer.

Claim Rejections - 35 USC § 103

9. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

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- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 10. Claims 3, 4, 5, 6, 12, 13, 14, 15, 19 and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tanaka et al., U.S. Patent 6,767,796 B2.
- Tanaka discloses a semiconductor process substantially as claimed. However, Tanaka fails to disclose the atomic percentage of hydrogen left in the sidewall spacers as claimed. Given the teachings of what is disclosed in the prior art, it is not inventive to discover the optimum or workable ranges by routine experimentation. "In re Aller, 220 F.2d 454, 456, 105 USPQ 233, 235 (CCPA 1955).

Objections

12. Claims 2, 7, 11 and 16 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Conclusion

- 13. Any inquiry concerning this communication or earlier communications from the examiner should be directed to W. David Coleman whose telephone number is 571-272-1856. The examiner can normally be reached on 9:00 AM-5:00 PM.
- 14. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent 15. Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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W. David Coleman Primary Examiner Art Unit 2823

WDC